

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	62	("205"/\$.ccls. "204"/\$.ccls. "438"/\$.ccls. "257"/\$.ccls. "216"/\$.ccls.) and (electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and bump and (current adj2 density) and etching with undercut	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/08 08:50
L2	300	("205"/\$.ccls. "204"/\$.ccls. "438"/\$.ccls. "257"/\$.ccls. "216"/\$.ccls.) and (electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and bump near5 solder and etching with undercut	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/08 08:51
L3	236	("205"/\$.ccls. "204"/\$.ccls. "438"/\$.ccls. "257"/\$.ccls. "216"/\$.ccls.) and (electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and bump near5 solder and etching near5 undercut	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/08 08:51

L4	233	("205"/\$.ccls. "204"/\$.ccls. "438"/\$.ccls. "257"/\$.ccls. "216"/\$.ccls.) and (electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and bump near5 solder and etching near5 undercut and \$5resist	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/08 08:51
L5	51	("205"/\$.ccls. "204"/\$.ccls. "438"/\$.ccls. "257"/\$.ccls. "216"/\$.ccls.) and (electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and bump near5 solder and chemical near3 etch\$3 near5 undercut and \$5resist	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/08 08:52
L6	134	("205"/\$.ccls. "204"/\$.ccls. "438"/\$.ccls. "257"/\$.ccls. "216"/\$.ccls.) and (electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and bump near5 solder and wet near3 etch \$3 near5 undercut and \$5resist	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/08 08:58
L8	84	6 not 5	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/08 08:59

L10	155	("205"/\$.ccls. "204"/\$.ccls. "438"/\$.ccls. "257"/\$.ccls. "216"/\$.ccls.) and (electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and bump near\$5 solder and wet near\$3 etch \$3 with undercut\$3 and \$5resist	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/08 09:07
L11	21	10 not 6	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/08 09:07
L12	335	("205"/\$.ccls. "204"/\$.ccls. "438"/\$.ccls. "257"/\$.ccls. "216"/\$.ccls.) and (electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and wet near\$3 etch\$3 with undercut\$3 and \$5resist	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/08 09:14
L13	128	("205"/\$.ccls. "204"/\$.ccls. "438"/\$.ccls. "257"/\$.ccls. "216"/\$.ccls.) and (electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) same solder and wet near\$3 etch\$3 with undercut\$3 and \$5resist	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/08 09:15
L14	8	13 not 10	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/08 09:15

L15	169	("205"/\$.ccls. "204"/\$.ccls. "438"/\$.ccls. "257"/\$.ccls. "216"/\$.ccls.) and (electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and solder and wet near3 etch\$3 with undercut\$3 and \$5resist	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/08 09:15
L16	14	15 not 10	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/08 09:16
L17	6	16 not 14	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/08 09:16
L18	335	("205"/\$.ccls. "204"/\$.ccls. "438"/\$.ccls. "257"/\$.ccls. "216"/\$.ccls.) and (electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and wet near3 etch\$3 with undercut\$3 and \$5resist	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/08 09:16
L19	144	("205"/\$.ccls. "204"/\$.ccls. "438"/\$.ccls. "257"/\$.ccls. "216"/\$.ccls.) and (electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and wet near3 etch\$3 with undercut\$3 same \$5resist	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/08 09:17
L20	76	19 not 10	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/08 09:17

L21	70	20 not 15	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/08 09:17
L22	145	(electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) same solder and wet near3 etch\$3 with undercut\$3 and \$5resist	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/08 09:22
L23	25	22 not 10	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/08 09:22
L24	17	23 not 15	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/08 09:22

5/ 8/ 2009 9:59:30 AM

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plating solder bump.wsp